# Superconducting properties of the composite-processed Nb<sub>3</sub>Sn superconductor with the Cu-Sn-Zn matrix

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Effects of the Zn addition to the Cu–Sn matrix of the Nb<sub>3</sub>Sn composite tape have been investigated by measuring the matrix work-hardening behaviour, the rate of Nb<sub>3</sub>Sn layer formation and the pertinent superconducting properties. The Zn addition drastically enhances the diffusion rate of Nb<sub>3</sub>Sn formation at each Sn level in the matrix examined, leading to sufficient superconducting properties even at a low Sn level of  $3.5 \, \text{at. \%}$ ; a sample containing  $3.5 \, \text{at. \%}$  Sn and  $15 \, \text{at. \%}$  Zn in the matrix exhibits a critical temperature and critical current density comparable with those of samples at a Sn level of  $7 \, \text{at. \%}$ . The upper critical field obtained for a sample with the 6 at. % Cu–6 at. % Sn–4 at. % Zn matrix beyond 200 kOe. The work-hardening of the composite matrix is found to be essentially a function of Sn level, and insensitive to the Zn addition.

# 1. Introduction

The difficulty in applying compound superconductors to practical superconducting systems arises from their extreme brittleness, thus having caused the development of various new fabrication processes. From the technological point of view, the socalled composite process [1] may be considered excellent because of its simplicity and potential to produce multifilamentary superconducting wires. In a typical composite process for producing an  $Nb_3Sn$  or  $V_3Ga$  wire, a composite consisting of an Nb core in a Cu-Sn alloy matrix or a V core in a Cu--Ga alloy matrix is cold-worked into a wire with repeated intermediate anneals, and exposed to subsequent heat treatment usually in the temperature range 700° C to 800° C for Nb<sub>3</sub>Sn or 600° C to 700° C for V<sub>3</sub>Ga formation. At present, the best superconducting properties commercially attainable are associated with materials from Nb<sub>3</sub>Sn or V<sub>3</sub>Ga. However, rapid growth of superconductive applications to date urgently demands further progress in superconducting materials. Recently, attempts have been made to improve superconducting properties of composite-processed Nb<sub>3</sub>Sn and V<sub>3</sub>Ga superconductors by adding a third element

to the core or/and the matrix. Zr-doping in the Nb [2] or the V [3] core has been found to refine the compound grains, resulting in remarkable enhancement of the critical current density,  $J_c$ . Sn [4] or Zr [2] addition to the Nb core has been reported to increase the growth rate of the Nb<sub>3</sub>Sn layer, whereas Al addition reduces the growth rate [5]. According to Weinman *et al.* [6] as well as Howe and Weinman [7], Ga addition to the V core gains substantial improvements in the growth rate and the  $J_c$  properties of the V<sub>3</sub>Ga layer.

Addition of a third element might be easier to the Cu-base matrix than to the core. Tachikawa et al. [8] have shown that the addition of Al to the Cu-Ga alloy matrix promotes the diffusional growth of a V<sub>3</sub>Ga layer, causing a considerable increase in critical current,  $I_e$ , without appreciable loss in ductility of the composite. Dew-Hughes et al. [5] have revealed that the addition of Al both to the Nb core and to the Cu-Sn alloy matrix can raise remarkably  $J_e$  of the Nb<sub>3</sub>Sn layer at fields up to 80 kOe. Al is known to form a wide range of solid solutions with  $\alpha$ -Cu [9], which contributes to the sufficient ductility of Cu-Sn-Al as well as Cu-Ga-Al solid solutions up to appropriate levels

(at. %)		
CSZ	Sn	Zn
30	3.5	0
34	3.5	4
38	3.5	8
310	3.5	10
315	3.5	15
50	5	0
54	5	4
58	5	8
60	6	0
64	6	4
70	7	0
74	7	4

TABLE I The chemical composition of matrix alloys

of Al content. In this respect, Zn exhibits much more extensive solubility in  $\alpha$ -Cu than Al does [10], so that effects similar to those brought about by Al addition might be expected through the Zn addition to the matrix. In the present study Zn was added to the Cu–Sn matrix of the compositeprocessed Nb<sub>3</sub>Sn, and effects of the Zn addition on the Nb<sub>3</sub>Sn formation and its superconducting properties were examined.

## 2. Experimental

The matrix alloys were cast as 15 mm diameter rods and machined to 13 mm diameter. An Nb core was inserted into an axial hole of 6 mm diameter drilled in the rod. Composite tapes with a cross-section of  $0.25 \text{ mm} \times 5 \text{ mm}$  were then fabricated by cold swaging and rolling with intermediate annealing at  $600^{\circ}$  C. The nominal compositions of the matrix alloys are shown in Table I.

Specimens cut from the tapes were sealed in silica capsules under an Ar-atmosphere and heat-treated at temperatures between  $650^{\circ}$  and  $850^{\circ}$  C for times up to 100 h. Specimen surfaces were then polished carefully and electroplated with Cu on both ends to be used for subsequent measurements. The superconducting critical temperature,  $T_{\rm c}$ , was determined by a standard resistive technique.  $I_{\rm c}$  was measured using a four-probe method in a liquid He bath under a transverse magnetic field of 65 kOe. Measurement of the upper critical field,  $H_{\rm c2}$ , was performed for some selected samples at the Francis Bitter National Magnet Laboratory.

After the  $I_c$  experiment, the cross-section of each sample was examined metallographically. The reacted layer thickness, d, was measured, which in turn was used for the calculation of  $J_c$ , The composition profile of the layers was inspected by electron-beam microprobe analysis. Fracture appearance of selected samples was examined by means of a scanning electron microscope to monitor the grain size of the Nb<sub>3</sub>Sn layers.

#### 3. Result and Discussion

#### 3.1. Ductility of matrix alloys

The ductility of matrix alloys was evaluated on the basis of a Vickers hardness measurement. An available Cu-Sn-Zn phase diagram [11], where the

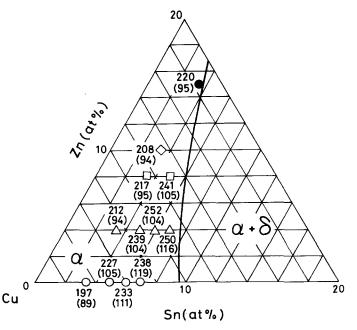


Figure 1 Isothermal section of the Cu-Sn-Zn phase at  $500^{\circ} C$  [11]. Numbers assigned to each mark of the matrix compositions with and without a bracket indicate Vickers hardness values for as-annealed and 50% cold-worked states, respectively.

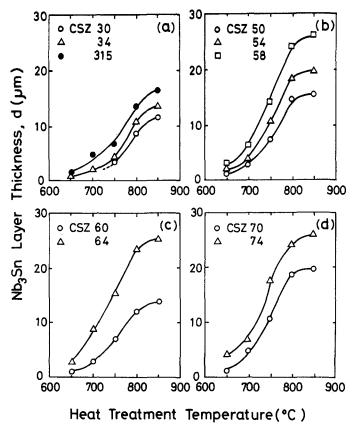


Figure 2 Nb<sub>3</sub> Sn reacted layer thickness as a function of heat treatment temperature, heating period being 100 h.

compositions of the present matrix alloys were plotted, Fig. 1, shows that all the compositions are within the  $\alpha$ -solid solution range, while some of them, namely CSZ315, CSZ58 and CSZ64, are situated very close to the  $\alpha/\alpha + \delta$  phase boundary. At a given Sn level, increasing Zn content causes a slight increase in hardness for the 50% coldworked state, as indicated in Fig. 1. However, the work-hardening behaviour of the matrix alloys depends more strongly on the Sn level than on the Zn level. It may be concluded that all the matrix alloys used in the present study have sufficient ductility at room temperature.

#### 3.2. Growth of the reacted layer

The thickness of the reacted Nb<sub>3</sub>Sn layer, d, is strongly affected by Zn addition. In Fig. 2a to d, d is plotted versus heating temperature, the heating period being 100 h. For CSZ30 heat-treated at  $650^{\circ}$  C as well as at 700° C, d was too small to be measured. The Nb<sub>3</sub>Sn layer growth rate increases with increasing temperature. Raising the Sn level in the matrix causes an evident increase in the growth rate for each temperature examined. At a given Sn level, the growth rate increases significantly with increasing Zn content. However, the most pronounced effect of the Zn addition on the growth rate is observed for intermediate Sn levels of 5 and 6 at. %. For example, a Zn addition of 15 at. % in CSZ315 causes a smaller increase in d than a Zn addition of 4 at. % in CSZ64 does. Lower d values for CSZ315, compared with those for CSZ64 may be attributed to premature Sn depletion in the matrix.

For a given compositon and heating temperature, a general equation

$$d = At^n$$

is known to hold empirically, where t is the heating period and n and A are constants. In Fig. 3 log d is plotted versus log t for four selected samples heated at 800° C for up to 100 h. n corresponds to the gradient of the straight lines drawn through the points and is found to be consistently around 0.5 for all these compositions. This implies that the Nb<sub>3</sub>Sn layer in these specimens is grown through a diffusional process. n values ranging from 0.35 to 1 have been reported on the growth of Nb<sub>3</sub>Sn [12], and the origin of different n values has been discussed [5]. But since rather thin reacted layers have been generally used to evaluate n

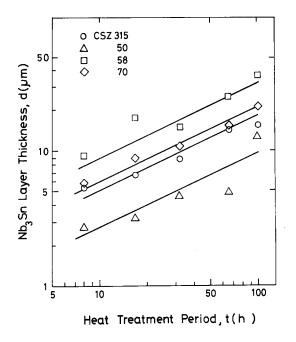


Figure 3 Logarithmic Nb<sub>3</sub>Sn layer thickness as a function of logarithmic heat treatment period, heating temperature being  $800^{\circ}$  C.

values, the irregular nature of the reacted-layer boundaries seems to reduce the reliability of this kind of discussion. In the present study relatively thick layers were the object of examination to avoid ambiguity with d. The constant A is significantly increased by raising the Sn level and also by the Zn addition as seen in Fig. 3. Microprobe analysis could detect no appreciable amount of Zn in the reacted layer in any of the samples. Dew-Hughes *et al.* [5] have found the presence of Al in the composite-processed Nb<sub>3</sub>Sn layer only when the Al was added both to the matrix and to the core, and the absence of Al in the Nb<sub>3</sub>Sn layer even when several at.% Al was added to the matrix alone. A consistent explanation of this effect is not given at present.

#### 3.3. Critical temperature and critical field

The superconducting critical temperature,  $T_{\rm c}$ , showed no systematic dependence on the Zn addition in any of the samples but CSZ315. In Figs. 4a to d,  $T_c$  is presented as a function of heating temperature, with the heating period being 100 h.  $T_{\rm c}$ increases with increasing temperature and seems to approach a saturation value at each Sn level. Raising the Sn level causes an increase in  $T_c$  at each heating temperature, but the Zn addition at any Sn level fails to make an essential increase in  $T_{c}$ . However, a Zn addition of 15 at. % at a Sn level of 3.5 at. % results in quite a large enhancement in  $T_{c}$  for the entire temperature range examined, and the effect is especially prominent at lower heating temperature.  $T_c$  values of CSZ315 are higher than those of any other sample at lower heating temperatures, and comparable with those of samples at Sn levels of 6 as well as 7 at. % at higher temperatures. The maximum in  $T_c$  reached about 17.6 K in the present study. The lower  $T_c$  values

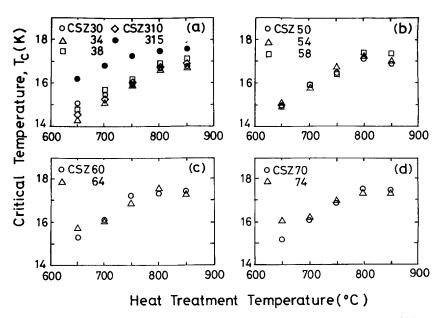


Figure 4 Critical temperature as a function of heat treatment temperature, heating period being 100 h. 1946

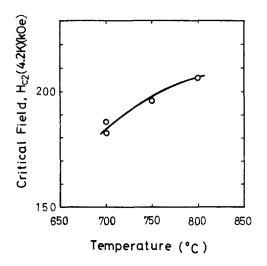


Figure 5 Critical field of CSZ64 as a function of heat treatment temperature, heating period being 100 h.

obtained for lower heating temperatures may be attributed to insufficient integrity of the ordered structure. The general behaviour of  $T_c$  in the present study is related to that of d, as pointed out by Luhman and Suenaga [4].

Measurement of the upper critical field,  $H_{c2}$ , was performed at 4.2 K on CSZ64 heat-treated at 700°, 750° and 800° C, respectively for 100 h, by means of a standard resistive method.  $H_{c2}$  values were determined by extrapolating H versus  $I_c$ curves to zero  $I_c$ .  $H_{c2}$  increases with increasing heat treatment temperature, as shown in Fig. 5. The  $H_{c2}(4.2 \text{ K})$  value for the 800° C heat-treated specimen is beyond 200 kOe. The general characteristics of  $H_{c2}$  with respect to the heating temperature are apparently consistent with those of  $T_c$ .

## 3.4. Critical current and critical current density

The critical current,  $I_c$ , was strongly affected by Zn addition. Fig. 6 represents  $I_c$  as a function of heating temperature. At each Sn level  $I_c$  increases with increasing Zn content. This increase in  $I_c$  is primarily due to the increase in *d*. The effect of the Zn addition is most prominent for intermediate Sn levels of 5 and 6 at. %. A 4 at. % Zn addition at Sn levels of 5 and 6 at. % causes a drastic increase in  $I_c$  while at a Sn level of 3.5 at. % more than

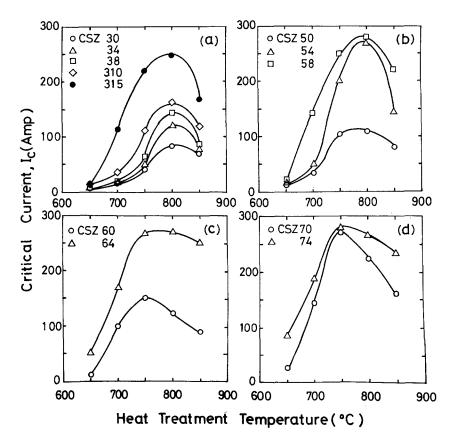


Figure 6 Critical current as a function of heat treatment temperature, heating period being 100 h.

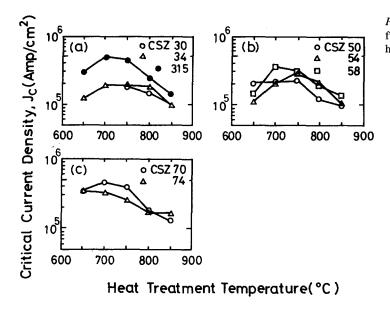


Figure 7 Critical current density as a function of heat treatment temperature, heating period being 100 h.

10 at. % Zn is necessary to gain as much in  $I_c$ . Temperatures corresponding to  $I_{e}$  maxima are nearly independent of the Zn addition at any Sn level, and lowered with raising Sn level. The reduction in  $I_{\rm c}$  at higher temperatures is attributed to the reduction of critical current density due to the grain coarsening. As concerns CSZ315,  $I_c$  is relatively larger than that expected from its d value and is comparably as high as that of samples at Sn levels of 6 and 7 at. %. In any event, it is feasible to conclude that comparable  $I_c$  values are obtained for samples whose matrix composition is situated near the  $\alpha/\alpha + \delta$  boundary as denoted in Fig. 1. Similar effects of substitution have been reported on a composite process of the  $V_3$ Ga tape where part of Ga in the Cu-Ga matrix is replaced by Al [13].

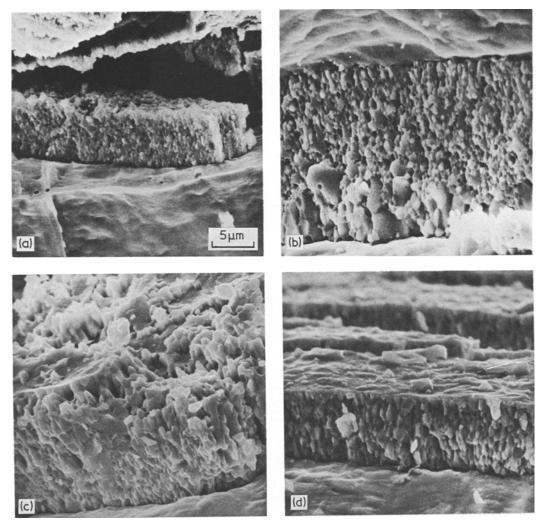
The critical current density,  $J_c$ , ranges between 1 and  $6 \times 10^5 \,\mathrm{A \, cm^{-2}}$ , as shown in Fig. 7a to c, and increases with increasing Sn level at each heat treatment temperature.  $J_c$  was found to be less sensitive to the Zn addition for specimens with the same heat treatment condition, regardless of that for CSZ315. The maximum in  $J_c$  seems to appear around 700° C for each sample. At higher temperatures grain coarsening is responsible for the lower  $J_c$  values obtained [14]. Fractographs of Fig. 8a to c reveal that grain coarsening of the reacted layers becomes apparent beyond 800° C, consistent with degradation of  $I_c$  and  $J_c$  as shown in Figs. 6 and 7, respectively. The grain size of CSZ315 heat-treated at 800° C for 100 h is nearly the same as that of CSZ50, as shown in Fig. 8d.

The degradation of  $J_c$  at 650° C is probably due to insufficient integrity of the reacted layer formed.  $J_c$  for CSZ315 is comparably as high as that of CSZ70 at each temperature, which is a rather explicit indication that the reacted layers of both these samples are nearly equal in integrity.

An empirical equation has been found which describes  $J_c$  at a given d in the following form [2];

$$J_{\mathbf{c}}(d) = J_{\mathbf{c}}(0) \exp\left(-nd\right)$$

where n is the slope of a  $\ln J_c(d)$  versus d plot and  $J_{\rm c}(0)$  is the extrapolated zero thickness value of  $J_{\rm c}(d)$  In Fig. 9 ln  $J_{\rm c}$  is plotted against d regardless of heating temperatures. At each Sn level straight lines can be drawn through the points corresponding to d values for the temperature range where  $T_{e}$ values go to saturation. n seems to be nearly consistent at a given Sn level and decreases with increasing Sn level. Because the grain boundary is a primary pinning centre in the Nb<sub>3</sub>Sn superconductor, the slope n is regarded as reflecting the graingrowth behaviour of each sample. The fact that ndoes not vary with Zn addition is compatible with the observation that Zn is not found in the reacted layer.  $J_{c}(0)$  shows a dependency on the Zn addition, in which  $J_{c}(0)$  increases with increasing Zn content. Since the Zn addition promotes the formation of Nb<sub>3</sub>Sn, the time required to grow a given thickness of Nb<sub>3</sub>Sn is shortened, and consequently the grain growth of Nb<sub>3</sub>Sn might be decreased by the Zn addition. Thus, in the specimens with Zn added the faster growth rate leads to a larger  $J_e$  value for a given thickness of Nb<sub>3</sub>Sn.



*Figure 8* Fracture appearances of composite tapes; (a) CSZ50 heat-treated at 750° C for 100 h, (b) CSZ50 heat-treated at 800° C for 100 h, (c) CSZ50 heat-treated at 850° C for 100 h, (d) CSZ315 heat-treated at 800° C for 100 h.

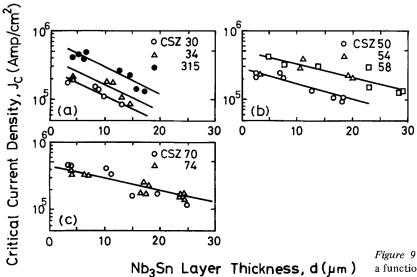


Figure 9 Logarithmic current density as a function of  $Nb_3 Sn$  layer thickness.

## 4. Conclusion

In the composite diffusion process of the Nb<sub>3</sub>Sn superconductor a substantial part of the Sn in the Cu-Sn matrix can be replaced by a rather large amount of Zn without any essential degradation in the superconducting critical values. The Zn addition causes a marked increase in  $I_{c}$  through increasing the growth rate of the Nb<sub>3</sub>Sn layer at each Sn level examined. Excellent  $I_{c}$  properties can be obtained even for samples containing only 3.5 at. % Sn in the matrix which otherwise leads to poor  $I_{c}$ values. The Zn does not dissolve into Nb<sub>3</sub>Sn and has no effect on the intrinsic superconducting properties, such as  $T_c$ , of Nb<sub>3</sub>Sn. However, the Zn may introduce excess vacancies in the Cu-Sn matrix. This increases the supply rate of Sn at the matrix-Nb<sub>3</sub>Sn diffusion interface and promotes the formation of an Nb<sub>3</sub>Sn layer.

The  $I_c$ ,  $J_c$  and  $T_c$  properties of CSZ315 (Cu-3.5 at.% Sn-15 at.% Zn alloy matrix) are comparable with those of samples containing 7 at.% Sn in the matrix. It is inferred that samples with matrix compositions adjacent to the  $\alpha/\alpha + \delta$ phase boundary in the Cu-Sn-Zn ternary system (Fig. 1) have approximately the same superconducting properties. A composite process making use of the Cu-Sn-Zn alloy as the matrix may be promising for fabricating the Nb<sub>3</sub>Sn multifilamentary wire, since the Zn addition causes an outstanding enhancement in the growth rate of the Nb<sub>3</sub>Sn even at low Sn levels without serious loss in the ductility of the composite.

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